

Product Information Sheet

MATERIAL ID:
EPO-TEK® 310T-M
Date: 03/2009

Per:
Rev: III

Material Description:

A two component, flexible epoxy designed for low stress applications in semiconductor, hybrid, medical, acoustical and optical industries. Replacement for EPO-TEK® 310T.

Number of Components:

Two

Mix Ratio by weight:

10:6

Cure Schedule (minimum)

65°C/2 Hours - 23°C/24 Hours

Specific Gravity:

--- Part A: 1.12 Part B: 1.08

Pot Life:

35 Minutes

Shelf Life:

One year at room temperature

NOTE: Container(s) should be kept closed when not in use. Filled systems should be stirred thoroughly before mixing and prior to use.

MATERIAL CHARACTERISTICS: *To be used as a guide only, not as a specification. Data below is not guaranteed. Different batches, conditions and applications yield differing results; Cure condition: 65°C/2 hours*

* denotes test on lot acceptance basis

PHYSICAL PROPERTIES:			
*Color (before cure):	Part A: Tan	Part B: Clear/Colorless	
*Consistency:	Slightly thixotropic paste		Die Shear @ 23°C: ≥ 3 Kg / 1020 psi
*Viscosity (23°C):			Degradation Temp: 401 °C
@ 100 rpm	1,800 - 3,300 cPs		Weight Loss:
Thixotropic Index:	2.1		@ 200°C: 0.05 %
*Glass Transition Temp:	≤ 30 °C (Dynamic Cure		@ 250°C: 0.18 %
20—200°C /ISO 25 Min; Ramp -10—200°C @ 20°C/Min)			@ 300°C: 0.63 %
Coefficient of Thermal Expansion (CTE):			Operating Temp:
Below Tg:	74 x 10 ⁻⁶ in/in°C		Continuous: - 55°C to + 200°C
Above Tg:	236 x 10 ⁻⁶ in/in°C		Intermittent: - 55°C to + 300°C
Shore A Hardness:	75		Storage Modulus @ 23°C: 1,223 psi
Lap Shear @ 23°C:	500 psi		*Particle Size: ≤ 20 microns

ELECTRICAL AND THERMAL PROPERTIES:			
Thermal Conductivity:	N/A	Dielectric Constant (1KHz):	5.10
Volume Resistivity @ 23°C:	≥ 2.5 x 10 ¹⁰ Ohm-cm	Dissipation Factor (1KHz):	0.091

OPTICAL PROPERTIES @ 23°C:	
Spectral Transmission:	N/A
Refractive Index (uncured):	N/A

EPOXY TECHNOLOGY, INC.
 14 FORTUNE DRIVE, BILLERICA, MA 01821 (978) 667-3805, FAX (978) 663-9782
 WEB SITE: www.epotek.com